

# SN54HC623, SN74HC623 OCTAL BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

SCLS149C – DECEMBER 1982 – REVISED DECEMBER 2002

- Wide Operating Voltage Range of 2 V to 6 V
- High-Current 3-State Outputs Can Drive Up To 15 LSTTL Loads
- Low Power Consumption, 80- $\mu$ A Max  $I_{CC}$
- Typical  $t_{pd} = 8$  ns
- $\pm 6$ -mA Output Drive at 5 V
- Low Input Current of 1  $\mu$ A Max
- Lock Bus-Latch Capability
- True Logic

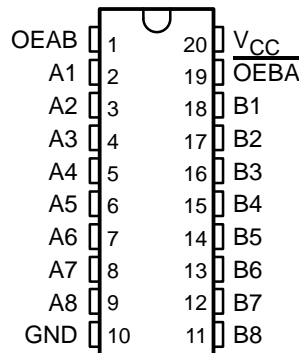
## description/ordering information

These octal bus transceivers are designed for asynchronous two-way communication between data buses. The control-function implementation allows for maximum flexibility in timing.

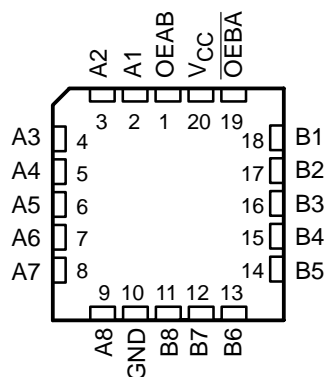
The 'HC623 devices allow data transmission from the A bus to the B bus or from the B bus to the A bus, depending upon the logic levels at the output-enable (OEAB and  $\overline{OEBA}$ ) inputs.

OEAB and  $\overline{OEBA}$  disable the device so that the buses are effectively isolated. The dual-enable configuration gives the transceivers the capability to store data by simultaneously enabling OEAB and  $\overline{OEBA}$ . Each output reinforces its input in this transceiver configuration. When both OEAB and  $\overline{OEBA}$  are enabled and all other data sources to the two sets of bus lines are in the high-impedance state, both sets of bus lines (16 total) remain at their last states. The 8-bit codes appearing on the two sets of buses are identical.

SN54HC623 . . . J OR W PACKAGE  
SN74HC623 . . . DW, N, OR NS PACKAGE  
(TOP VIEW)



SN54HC623 . . . FK PACKAGE  
(TOP VIEW)



## ORDERING INFORMATION

TA	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	PDIP – N	Tube	SN74HC623N	SN74HC623N
	SOIC – DW	Tube	SN74HC623DW	HC623
		Tape and reel	SN74HC623DWR	
	SOP – NS	Tape and reel	SN74HC623NSR	HC623
-55°C to 125°C	CDIP – J	Tube	SNJ54HC623J	SNJ54HC623J
	CFP – W	Tube	SNJ54HC623W	SNJ54HC623W
	LCCC – FK	Tube	SNJ54HC623FK	SNJ54HC623FK

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).



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 **TEXAS  
INSTRUMENTS**

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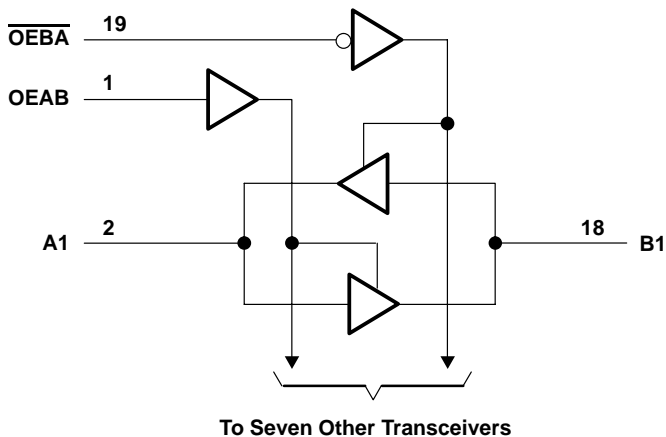
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FUNCTION TABLE

INPUTS		OPERATION
$\overline{\text{OEBA}}$	OEAB	
L	L	B data to A bus
H	H	A data to B bus
H	L	Isolation
L	H	B data to A bus, A data to B bus

## logic diagram (positive logic)



## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, $V_{CC}$	-0.5 V to 7 V
Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{CC}$ ) (see Note 1)	$\pm 20$ mA
Output clamp current, $I_{OK}$ ( $V_O < 0$ or $V_O > V_{CC}$ ) (see Note 1)	$\pm 20$ mA
Continuous output current, $I_O$ ( $V_O = 0$ to $V_{CC}$ )	$\pm 35$ mA
Continuous current through $V_{CC}$ or GND	$\pm 70$ mA
Package thermal impedance, $\theta_{JA}$ (see Note 2): DW package	58°C/W
N package	69°C/W
NS package	60°C/W
Storage temperature range, $T_{stg}$	-65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.  
2. The package thermal impedance is calculated in accordance with JESD 51-7.

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## recommended operating conditions (see Note 3)

		SN54HC623			SN74HC623			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V <sub>CC</sub>	Supply voltage	2	5	6	2	5	6	V
V <sub>IH</sub>	High-level input voltage	V <sub>CC</sub> = 2 V		1.5	1.5		V	
		V <sub>CC</sub> = 4.5 V		3.15	3.15			
		V <sub>CC</sub> = 6 V		4.2	4.2			
V <sub>IL</sub>	Low-level input voltage	V <sub>CC</sub> = 2 V			0.5		V	
		V <sub>CC</sub> = 4.5 V			1.35			
		V <sub>CC</sub> = 6 V			1.8			
V <sub>I</sub>	Input voltage	0		V <sub>CC</sub>	0		V <sub>CC</sub>	V
V <sub>O</sub>	Output voltage	0		V <sub>CC</sub>	0		V <sub>CC</sub>	V
Δt/Δv	Input transition rise/fall time	V <sub>CC</sub> = 2 V			1000		ns	
		V <sub>CC</sub> = 4.5 V			500			
		V <sub>CC</sub> = 6 V			400			
T <sub>A</sub>	Operating free-air temperature	-55		125	-40		85	°C

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V <sub>CC</sub>	T <sub>A</sub> = 25°C			SN54HC623		SN74HC623		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V <sub>OH</sub>	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>	I <sub>OH</sub> = -20 μA	2 V	1.9	1.998	1.9	1.9	V		
			4.5 V	4.4	4.499	4.4	4.4			
			6 V	5.9	5.999	5.9	5.9			
		I <sub>OH</sub> = -6 mA	4.5 V	3.98	4.3	3.7	3.84			
			6 V	5.48	5.8	5.2	5.34			
V <sub>OL</sub>	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>	I <sub>OL</sub> = 20 μA	2 V	0.002	0.1	0.1	0.1	V		
			4.5 V	0.001	0.1	0.1	0.1			
			6 V	0.001	0.1	0.1	0.1			
		I <sub>OL</sub> = 6 mA	4.5 V	0.17	0.26	0.4	0.33			
			6 V	0.15	0.26	0.4	0.33			
I <sub>I</sub>	OEAB or OEBA	V <sub>I</sub> = V <sub>CC</sub> or 0	6 V	±0.1	±100	±1000	±1000	nA		
I <sub>OZ</sub>	A or B	V <sub>O</sub> = V <sub>CC</sub> or 0	6 V	±0.01	±0.5	±10	±5	μA		
I <sub>CC</sub>		V <sub>I</sub> = V <sub>CC</sub> or 0, I <sub>O</sub> = 0	6 V		8	160	80	μA		
C <sub>i</sub>	OEAB or OEBA		2 V to 6 V	3	10	10	10	pF		

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# SN54HC623, SN74HC623 OCTAL BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

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switching characteristics over recommended operating free-air temperature range,  $C_L = 50$  pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC}$	$T_A = 25^\circ\text{C}$			SN54HC623		SN74HC623		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
$t_{pd}$	A or B	B or A	2 V		29	105	160	130	ns		
			4.5 V		10	21	32	26			
			6 V		8	18	27	22			
$t_{en}$	$\overline{OEBA}$	A	2 V		112	210	315	265	ns		
			4.5 V		27	42	63	53			
			6 V		20	36	54	45			
$t_{dis}$	$\overline{OEBA}$	A	2 V		40	150	225	190	ns		
			4.5 V		18	30	45	38			
			6 V		16	26	38	32			
$t_{en}$	OEAB	B	2 V		112	210	315	265	ns		
			4.5 V		27	42	63	53			
			6 V		20	36	54	45			
$t_{dis}$	OEAB	B	2 V		40	150	225	190	ns		
			4.5 V		18	30	45	38			
			6 V		16	26	38	32			
$t_t$		A or B	2 V		20	60	90	75	ns		
			4.5 V		8	12	18	15			
			6 V		6	10	15	13			

switching characteristics over recommended operating free-air temperature range,  $C_L = 150$  pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC}$	$T_A = 25^\circ\text{C}$			SN54HC623		SN74HC623		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
$t_{pd}$	A or B	B or A	2 V		44	135	200	170	ns		
			4.5 V		14	27	40	34			
			6 V		11	23	34	29			
$t_{en}$	$\overline{OEBA}$	A	2 V		130	270	405	335	ns		
			4.5 V		31	54	81	67			
			6 V		23	46	69	56			
	OEAB	B	2 V		130	270	405	335	ns		
			4.5 V		31	54	81	67			
			6 V		23	46	69	56			
$t_t$		A or B	2 V		45	210	315	265	ns		
			4.5 V		17	42	63	53			
			6 V		13	36	53	45			

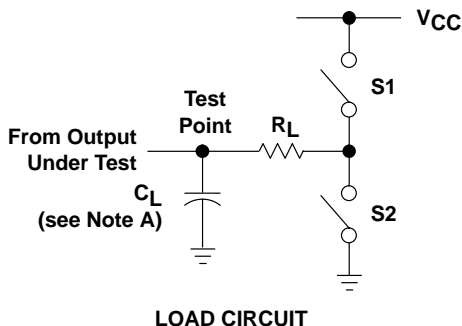
operating characteristics,  $T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	TYP	UNIT
$C_{pd}$ Power dissipation capacitance per transceiver	No load	40	pF

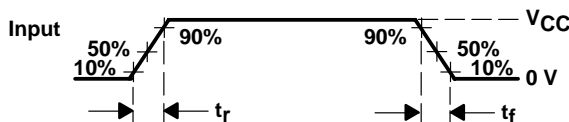
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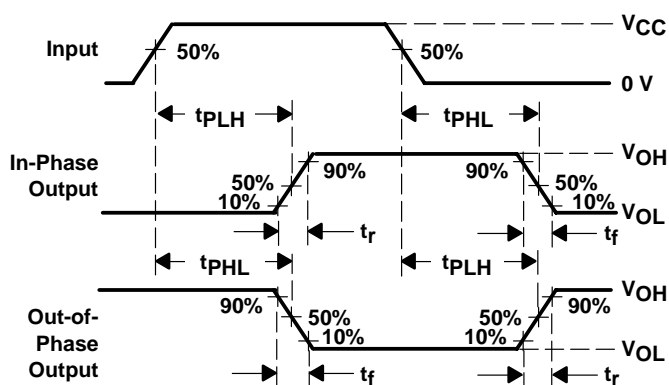
PARAMETER MEASUREMENT INFORMATION



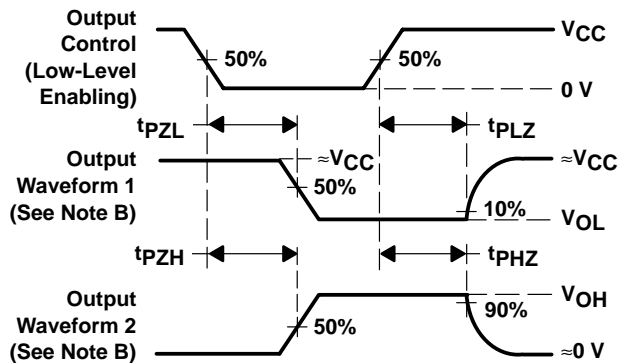
PARAMETER	RL	CL	S1	S2
ten	1 kΩ	50 pF or 150 pF	Open	Closed
			Closed	Open
tdis	1 kΩ	50 pF	Open	Closed
			Closed	Open
tpd or tt	—	50 pF or 150 pF	Open	Open



VOLTAGE WAVEFORM  
 INPUT RISE AND FALL TIMES



VOLTAGE WAVEFORMS  
 PROPAGATION DELAY AND OUTPUT TRANSITION TIMES



VOLTAGE WAVEFORMS  
 ENABLE AND DISABLE TIMES FOR 3-STATE OUTPUTS

- NOTES: A. CL includes probe and test-fixture capacitance.  
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.  
 C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, ZO = 50 Ω, tr = 6 ns, tf = 6 ns.  
 D. The outputs are measured one at a time with one input transition per measurement.  
 E. tpLZ and tpHZ are the same as tdis.  
 F. tpZL and tpZH are the same as ten.  
 G. tPLH and tPHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms

**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/ Ball Finish	MSL Peak Temp <sup>(3)</sup>	Samples (Requires Login)
SN74HC623DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributor or Sales Office
SN74HC623DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributor or Sales Office
SN74HC623N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	Contact TI Distributor or Sales Office
SN74HC623NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	Contact TI Distributor or Sales Office
SN74HC623NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	<a href="#">Purchase Samples</a>
SN74HC623NSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	<a href="#">Purchase Samples</a>
SN74HC623NSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	<a href="#">Purchase Samples</a>

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

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**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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**TAPE AND REEL INFORMATION**
**REEL DIMENSIONS**

**TAPE DIMENSIONS**


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

**TAPE AND REEL INFORMATION**

\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HC623NSR	SO	NS	20	2000	330.0	24.4	8.2	13.0	2.5	12.0	24.0	Q1



TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74HC623NSR	SO	NS	20	2000	367.0	367.0	45.0

N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - The 20 pin end lead shoulder width is a vendor option, either half or full width.

DW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.
  - This drawing is subject to change without notice.
  - Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
  - Falls within JEDEC MS-013 variation AC.

DW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



4209202-4/E 07/11

- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Refer to IPC7351 for alternate board design.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
  - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

# MECHANICAL DATA

NS (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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